

## Performance Specification

Model	Marking	V <sub>max</sub> (V dc)	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Typ. (W)	Maximum Time To Trip		Resistance	
							Current (A)	Time (Sec)	R <sub>i min</sub> (Ω)	R <sub>1max</sub> (Ω)
0603L010/24YR	1	24.0	35	0.10	0.30	0.5	0.5	1.00	0.900	6.000

V<sub>max</sub> = Maximum operating voltage device can withstand without damage at rated current (I<sub>max</sub>).

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).

I<sub>hold</sub> = Hold Current. Maximum current device will not trip in 25°C still air.

I<sub>trip</sub> = Trip Current. Minimum current at which the device will always trip in 25°C still air.

P<sub>d</sub> = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R<sub>i min/max</sub> = Minimum/Maximum device resistance prior to tripping at 25°C.

R<sub>1max</sub> = Maximum device resistance is measured one hour post reflow.

## Environmental Specifications

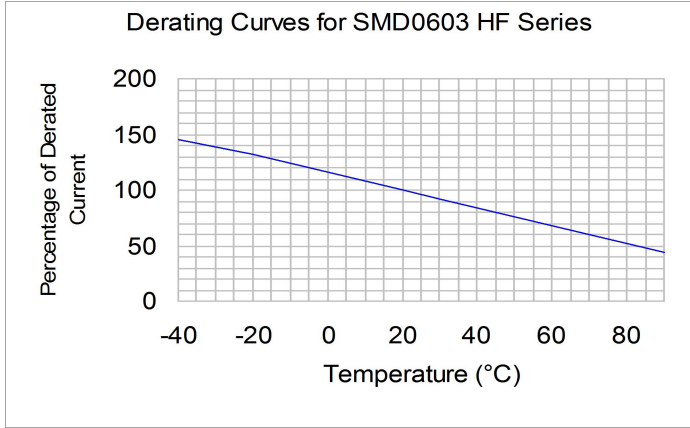
Test	條件	符合條件
Passive aging	+85°C, 1000 hrs.	I HOLD/I TRIP PASS
Humidity aging	+85°C, 85% R.H. , 168 hours	I HOLD/I TRIP PASS
Thermal shock	+85°C to -40°C, 20 times	I HOLD/I TRIP PASS
Resistance to solvent	MIL-STD-202,Method 215	电阻不變化
Vibration	MIL-STD-202,Method 201	电阻不變化
操作條件環境: - 40 ° C~+85° C		
在跳閘狀態下產品的表面最高溫度為125° C		

## Thermal Derating Chart

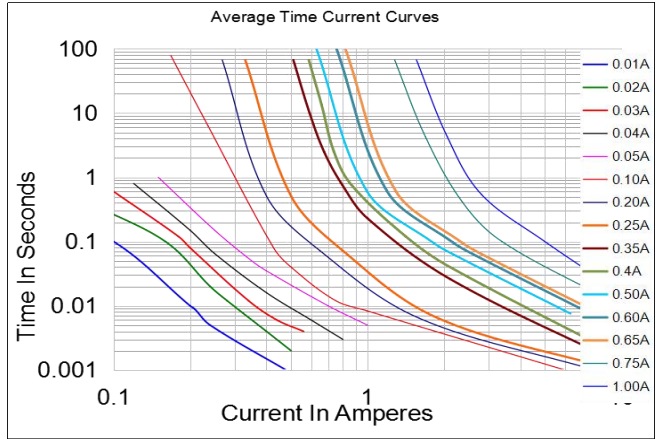
Recommended Hold Current(A) at Ambient Temperature(°C)

Model	Ambient Operation Temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
0603L010/24YR	0.13	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03

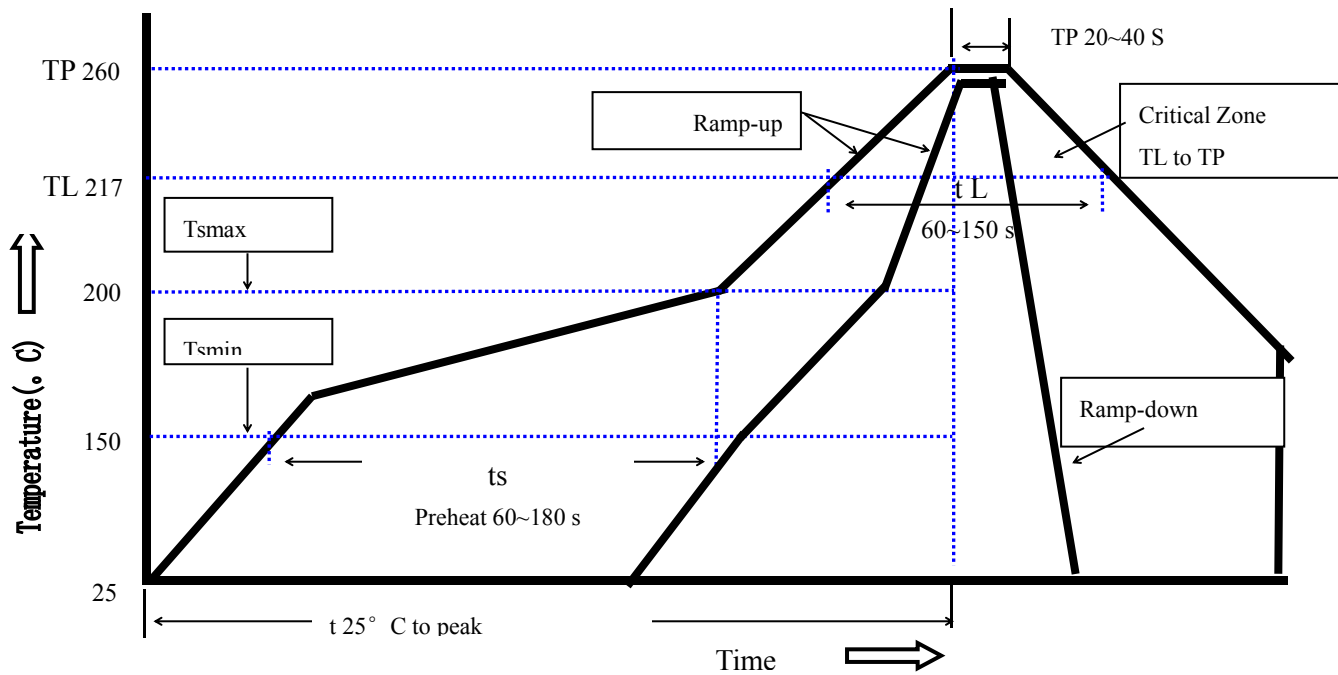
### Thermal Derating Curve



### Average Time-Current Curve



### Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(Ts max to T p)	3°C/second max.
Preheat	
-Temperature Min(Ts min)	150°C
-Temperature Max(Ts max)	200°C
-Time(Ts min to Ts max)	60~180 seconds
Time maintained above:	
-Temperature(TL)	217°C

-Time(tL)	60~150 seconds
Peak Temperature(Tp)	260°C
Ramp-Down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max
Storage Condition	0°C~30°C,30%-60%RH

Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free

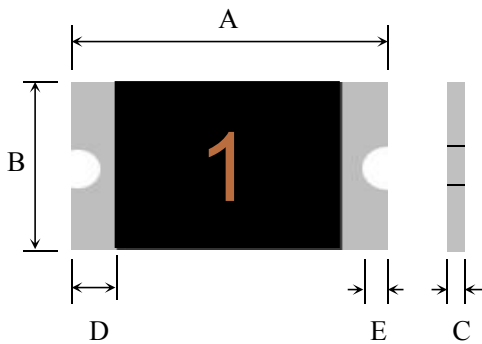
Recommended maximum paste thickness is 0.25mm

Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

### Physical Dimensions(mm.)



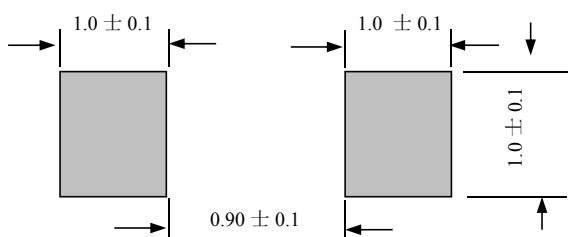
型號	A		B		C		D	E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
0603L010/24YR	1.45	1.85	0.65	1.05	0.40	1.00	0.15	0.10

#### Termination Pad Characteristics

Terminal pad materials: Tin-plated Nickel-Copper

Terminal pad solder ability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

### Recommended Pad Layout (mm.)



注：在此印锡面积条件下，推荐钢网厚度为 $\geq 0.12\text{MM}$ (钢网厚度不够要增大刷锡面积)

### Packaging Quantity

Part Number	Quantity
0603L010/24YR	4,000 pcs/reel

Tape & reel packaging per EIA481-1